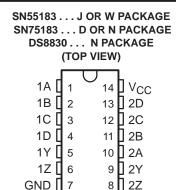
- Single 5-V Supply
- **Differential Line Operation**
- **Dual Channels**
- **TTL Compatibility**
- **Short-Circuit Protection of Outputs**
- **Output Clamp Diodes to Terminate Line Transients**
- **High-Current Outputs**
- **Quad Inputs**
- Single-Ended or Differential AND/NAND **Outputs**
- **Designed for Use With Dual Differential Drivers SN55182 and SN75182**
- Designed to Be Interchangeable With National Semiconductor DS7830 and **DS8830**

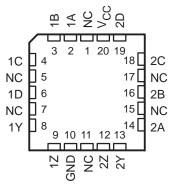
#### description

The DS8830, SN55183, and SN75183 dual differential line drivers are designed to provide differential output signals with high current capability for driving balanced lines, such as twisted pair, at normal line impedances without high power dissipation. These devices can be used as TTL expander/phase splitters, because the output stages are similar to TTL totem-pole outputs.



SN55183...FK PACKAGE (TOP VIEW)

GND [ 7



NC - No internal connection

#### **THE DS8830 AND SN55183 ARE** NOT RECOMMENDED FOR NEW DESIGNS

The driver is of monolithic single-chip construction, and both halves of the dual circuits use common power supply and ground terminals.

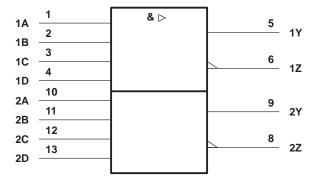
The SN55183 is characterized for operation over the full military temperature range of -55°C to 125°C. The DS8830 and SN75183 are characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

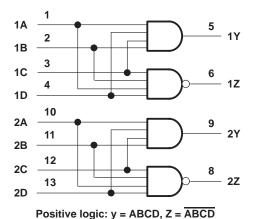


### logic symbol†



 $<sup>^\</sup>dagger$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

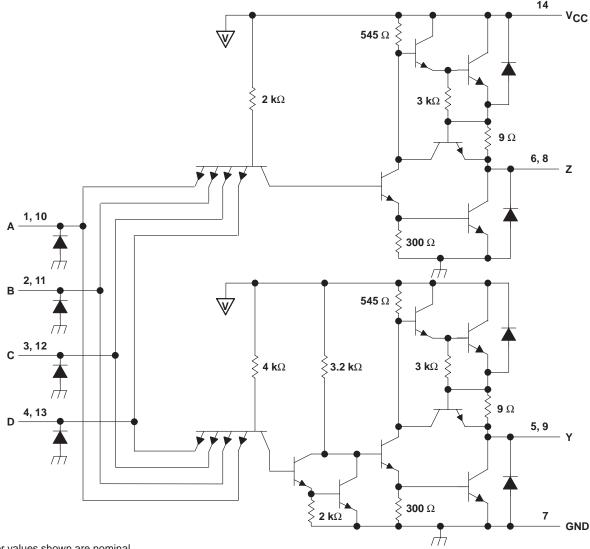
### logic diagram (positive logic)



Pin numbers shown are for the D, J, N, and W packages.



### schematic (each driver)



Resistor values shown are nominal.

Pin numbers shown are for the D, J, N, and W packages.

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage, V <sub>I</sub>	5.5 V
Duration of output short circuit (see Note 2)	1 s
Continuous total power dissipation	See Dissipation Rating Table
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or N package	ge 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package	300°C
Case temperature for 60 seconds, T <sub>c</sub> : FK package	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to network ground terminal.
  - 2. Not more than one output should be shorted to ground at any one time.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	**		T <sub>A</sub> = 125°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW	_
FK <sup>‡</sup>	1375 mW	11.0 mW/°C	880 mW	275 mW
J‡	1375 mW	11.0 mW/°C	880 mW	275 mW
N	1150 mW	9.2 mW/°C	736 mW	-
w‡	1000 mW	8.0 mW/°C	640 mW	200 mW

<sup>‡</sup> In the FK, J, and W packages, SN55183 chips are alloy mounted and SN75183 chips are glass mounted.

### recommended operating conditions

		SN55183			DS8830, SN75183			
	MIN	NOM	MAX	MIN	NOM	MAX		
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V	
High-level input voltage, VIH	2			2			V	
Low-level input voltage, V <sub>IL</sub>			0.8			0.8	V	
High-level output current, IOH			-40			-40	mA	
Low-level output current, IOL			40			40	mA	
Operating free-air temperature, TA	-55		125	0		70	°C	



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### electrical characteristics over recommended ranges of V<sub>CC</sub> and operating free-air temperature (unless otherwise noted)

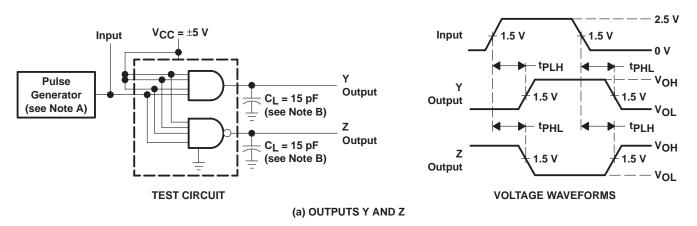
	PARAMETER		Т	EST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
Va	High-level output voltage	Y (AND) outputs	V <sub>IH</sub> = 2 V	$I_{OH} = -0.8 \text{ mA}$	2.4			V
VOH	High-level output voltage	Y (AND) outputs	VIH = 2 V	$I_{OH} = -40 \text{ mA}$	1.8	3.3		V
Voi	Low-level output voltage	Y (AND) outputs	\/ = 0.9.\/	I <sub>OL</sub> = 32 mA		0.2		V
VOL	Low-level output voltage	f (AND) outputs	V   L = 0.6 V	I <sub>DL</sub> = 0.8 V			0.4	V
Va	High-level output voltage	Z (NAND) outputs	V <sub>II</sub> = 0.8 V	$I_{OH} = -0.8 \text{ mA}$	2.4			V
VOH	r light-level output voltage	2 (NAND) outputs	VIL = 0.8 V	$I_{OH} = -40 \text{ mA}$	1.8	3.3		V
\/a:	Low-level output voltage	Z (NAND) outputs	V 2 V	I <sub>OL</sub> = 32 mA		0.2		V
VOL	Low-level output voltage	2 (NAND) outputs	V <sub>IH</sub> = 2 V	$I_{OL} = 40 \text{ mA}$		0.22	0.4	V
lн	High-level input current		V <sub>IH</sub> = 2.4 V				120	μΑ
Ц	Input current at maximum	input voltage	V <sub>IH</sub> = 5.5 V				2	mA
I <sub>IL</sub>	Low-level input current		V <sub>IL</sub> = 0.4 V				-4.8	mA
los	Short-circuit output current	<u></u>	V <sub>CC</sub> = 5 V,	T <sub>A</sub> =125°C§	-40	-100	-120	mA
Icc	Supply current (average pe	er driver)	V <sub>CC</sub> = 5 V,	All inputs at 5 V, No loa	ıd	10	18	mA

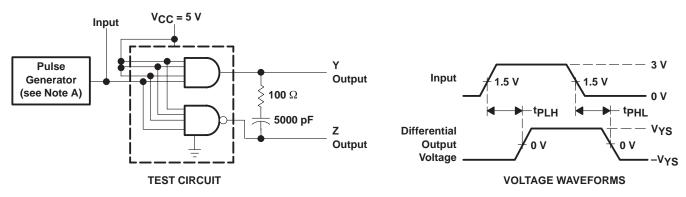
## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level Y output	AND gates	C <sub>L</sub> = 15 pF, See Figure 1(a)		8	12	ns
tPHL	Propagation delay time, high- to low-level Y output	AND gates	C <sub>L</sub> = 15 pF, See Figure 1(a)		12	18	ns
tPLH	Propagation delay time, low- to high-level Z output	NAND gates C <sub>L</sub> = 15 pF, See Figure 1(a)			6	12	ns
tPHL	Propagation delay time, high- to low-level Z output	NAND gates	C <sub>L</sub> = 15 pF, See Figure 1(a)		6	8	ns
tPLH	Propagation delay time, low- to high-level differential output	Y output with re $R_L = 100 \Omega$ in s See Figure 1(b)		9	16	ns	
tPHL	Propagation delay time, high- to low-level differential output	Y output with re $R_L = 100 \Omega$ in s See Figure 1(b)		8	16	ns	

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ Not more than one output should be shorted to ground at a time, and duration of the short circuit should not exceed one second. § T<sub>A</sub> = 125°C is applicable to SN55183 only.

#### PARAMETER MEASUREMENT INFORMATION





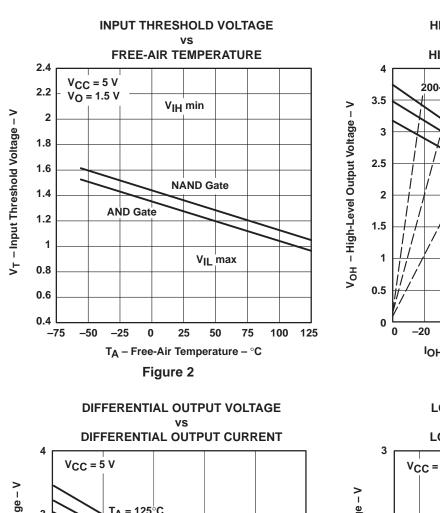
(b) DIFFERENTIAL OUTPUT

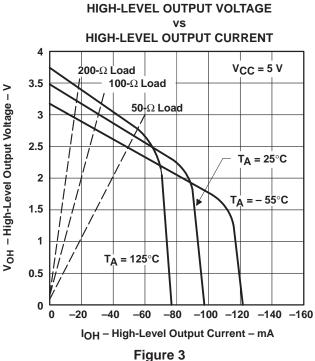
NOTES: A. The pulse generators have the following characteristics:  $Z_O = 50 \ \Omega$ ,  $t_f \le 10 \ ns$ ,  $t_f \le 10 \ ns$ ,  $t_W = 0.5 \ \mu s$ , PRR  $\le 1 \ MHz$ .

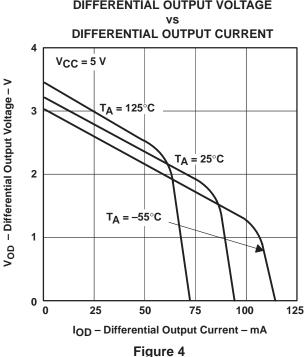
- B. C<sub>L</sub> includes probe and jig capacitance.
- C. Waveforms are monitored on an oscilloscope with  $r_i \ge 1 \text{ M}\Omega$ .

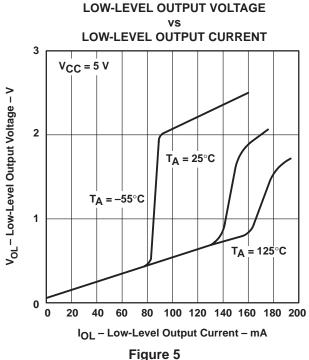
Figure 1. Test Circuits and Voltage Waveforms

#### TYPICAL CHARACTERISTICS†



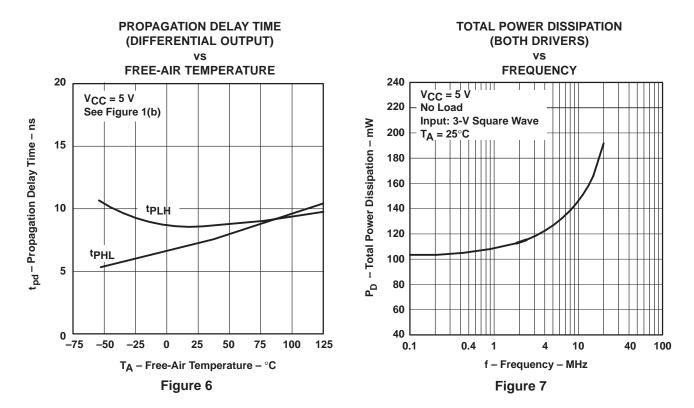






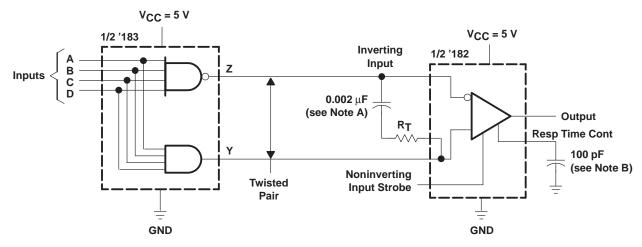
<sup>†</sup> Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

#### TYPICAL CHARACTERISTICS<sup>†</sup>



<sup>†</sup>Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

#### **APPLICATION INFORMATION**



NOTES: A. When the inputs are open circuited, the output is high. A capacitor may be used for dc isolation of the line-terminating resistor.

At the frequency of operation, the impedance of the capacitor should be relatively small.

$$\begin{split} \text{Example: let} \quad & f = 5 \text{ MHz} \\ \quad & C = 0.002 \, \mu\text{F} \\ Z_{\text{(circuit)}} = \frac{1}{2\pi\text{fC}} = \frac{1}{2\pi(5\times10^6)(0.002\times10^{-6})} \\ Z_{\text{(circuit)}} \approx & 16\Omega \end{split}$$

B. Use of a capacitor to control response time is optional.

Figure 8. Transmission of Digital Data Over Twisted-Pair Line

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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7900901VCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7900901VC A SNV55183J	Samples
7900901CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7900901CA SNJ55183J	Samples
SN55183J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN55183J	Samples
SN75183D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75183	Samples
SN75183DE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75183	Samples
SN75183N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75183N	Samples
SN75183NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75183N	Samples
SN75183NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75183	Samples
SNJ55183J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7900901CA SNJ55183J	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

<sup>(3)</sup> MSL. Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

### PACKAGE OPTION ADDENDUM

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(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN55183, SN55183-SP, SN75183:

Catalog: SN75183, SN55183

Military: SN55183

Space : SN55183-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

### **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	<u> </u>
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75183NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	SN75183NSR	SO	NS	14	2000	853.0	449.0	35.0	

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# D (R-PDSO-G14)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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